

(1.27 mm) .050"

SEAM SERIES

HIGH-SPEED/HIGH-DENSITY OPEN-PIN-FIELD

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?SEAM

Insulator Material:

Black LCP

Contact Material:

Copper Alloy

Operating Temp Range:

-55 °C to +125 °C

Current Rating

(7 mm stack height):

1.8 A per pin
(10 adjacent pins powered)

Plating:

Au or Sn over

50 μ" (1.27 μm) Ni

Contact Resistance:

5.5 mΩ

Working Voltage:

240 VAC

RoHS Compliant:

Yes

Lead-Free Solderable:

Yes

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



FILE NO. E111594

STANDARDS

- PISMO 2
- VITA 47
- VITA 57.1

PROTOCOLS

- 100 GbE
- Fibre Channel
- Rapid I/O
- PCI Express®
- SATA
- InfiniBand™

| MATED HEIGHTS | | | |
|-----------------------|-----------------|---------|---------|
| SEAM LEAD STYLE | SEAF LEAD STYLE | | |
| | −05.0 | −06.0 | −06.5 |
| −02.0 | 7 mm | 8 mm | 8.5 mm |
| −03.0 | 8 mm | 9 mm | 9.5 mm |
| −03.5 | 8.5 mm | 9.5 mm | 10 mm |
| −06.5 | 11.5 mm | 12.5 mm | 13 mm |
| −07.0 | 12 mm | 13 mm | 13.5 mm |
| −09.0 | 14 mm | 15 mm | 15.5 mm |
| −11.0 | 16 mm | 17 mm | 17.5 mm |

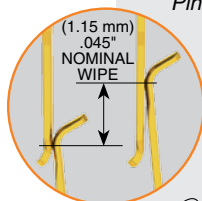
Notes:
Patented

IPC-A-610F and
IPC J-STD-001F Class 3
solder joint.

Some sizes, styles and
options are non-standard,
non-returnable.

Mates with:
SEAF, SEAFP

Standoffs:
JSO



Up to 500
Pins

5, 8 and 10 row footprint
compatible with SamArray®.
Samples recommended.

Solder
charges

Low
insertion/
extraction
forces

HIGH-SPEED CHANNEL PERFORMANCE

SEAM/SEAF @ 10 mm Mated Stack Height

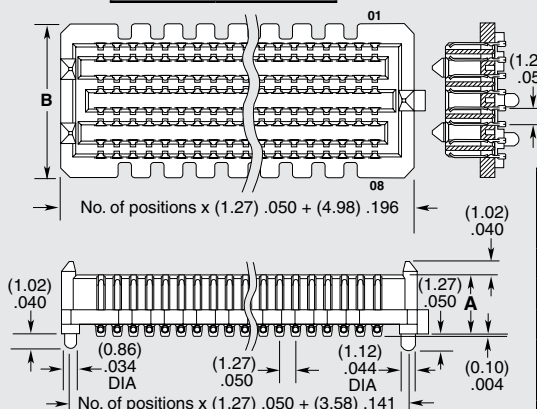
Rating based on Samtec reference channel.
For full SI performance data visit Samtec.com
or contact SIG@samtec.com

34
Gbps



| SEAM | NO. PINS PER ROW | LEAD STYLE | PLATING OPTION | NO. OF ROWS | SOLDER TYPE | A | K | TR |
|------|---|-------------------------------|--|---|---|--|---|----|
| | | Specify LEAD STYLE from chart | | | | | | |
| | -10, -15, -20, -30, -40, -50 (-10 only available in 04 row) (-15 is only available in 4 Row with -02.0 lead style and 10 row with any lead style) | | -L = 10 μ" (0.25 μm) Gold on contact area, Matte Tin on solder tail -S = 30 μ" (0.76 μm) Gold on contact area, Matte Tin on solder tail | -04 = Four Rows (-06.5 not available) -05 = Five Rows (-06.5 not available) -06 = Six Rows (-06.5 not available) -08 = Eight Rows -10 = Ten Rows | -1 = Tin/Lead Alloy Solder Charge -2 = Lead-Free Solder Charge | -A = Alignment Pins (Required. Arrays will not self-center on solder pads) -K = Polyimide film Pick & Place Pad -TR = Tape & Reel | | |

| NO. OF ROWS | B |
|-------------|--------------|
| -04 | (7.06) .278 |
| -05, -06 | (9.60) .378 |
| -08 | (12.14) .478 |
| -10 | (14.68) .578 |



| LEAD STYLE | A |
|------------|--------------|
| -02.0 | (4.60) .181 |
| -03.0 | (5.59) .220 |
| -03.5 | (6.10) .240 |
| -06.5 | (9.14) .360 |
| -07.0 | (9.60) .378 |
| -09.0 | (11.60) .457 |
| -11.0 | (13.60) .535 |

DIFFERENTIAL

| ARRAY | PAIR COUNT |
|-------|------------|
| 40x8 | 80 |
| 40x6 | 60 |
| 30x10 | 75 |
| 30x8 | 60 |
| 30x6 | 45 |
| 20x10 | 50 |
| 20x8 | 40 |
| 20x5 | 25 |

ALSO AVAILABLE (MOQ Required)

- Up to 560 pins
Contact Samtec.